

**IN THE CLAIMS**

This listing of claims replaces all prior listings:

1. (Currently Amended) A synthetic resin card comprising:  
a substantially planar core ~~layer~~ section; and  
a first outer layer and a second outer layer laminated on front and back surfaces of the  
core ~~layer~~ section, respectively,

wherein,

the first outer layer and the second outer layer have molecular orientations,

the first outer layer and the second outer layer are adhered directly to the front and  
back surfaces of the core section by means of a thermal pressing and are symmetrically  
bonded to the core section, and

the difference  $\Delta$  in the angle of orientation between the first and second outer  
layers is  $20^\circ$  or less causing the synthetic resin card warpage to be 1.5 mm or less; and at  
least one of the first and second outer layers is provided with a recording layer.

2. (Currently Amended) The synthetic resin card according to claim 1,

wherein,

the thicknesses of the first and second outer layers are symmetrical with respect to the  
core ~~layer~~ section.

3. (Currently Amended) The synthetic resin card according to claim 1,

wherein,

the first and second outer layers each have a thickness of 25 to 125  $\mu\text{m}$ .

4. (Currently Amended) The synthetic resin card according to claim 1,

wherein,

the first and second outer layers are each formed of a biaxially oriented film.

5. (Currently Amended) The synthetic resin card according to claim 4,  
wherein,

the biaxially oriented film ~~is composed of~~ comprises an oriented PET material.

6. (Currently Amended) The synthetic resin card according to claim 1,  
wherein,

the core ~~layer~~ section comprises a first core layer and a second core layer between which  
is sandwiched an electric module ~~sandwiched between a pair of core components~~.

7. (Currently Amended) The synthetic resin card according to claim 6,  
wherein,

~~the electronic module comprises an IC chip and an IC module connected to the IC~~  
chip first and second outer layers comprise films selected from the group consisting of  
polyethylene terephthalate (PET), polyethylene naphthalate (PEN), polypropylene (PP),  
polyphenylene sulfide (PPS), polystyrene, polyamides, polyvinyl chloride (PVC) and  
polyvinylidene chloride.

8. (Canceled)

9. (Currently Amended) The synthetic resin card according to claim 1,  
wherein,

the recording layer is composed of a reversible thermosensitive material.

10. (Currently Amended) The synthetic resin card according to claim 1,  
wherein,

the core ~~layer~~ section is composed of a copolymer of terephthalic acid, cyclohexanedimethanol, and ethylene glycol, and polycarbonate, the compounding ratio of the copolymer being 70% or less.

11. (Currently Amended) The synthetic resin card according to claim 1,

wherein,

the core ~~layer~~ section and the first and second outer layers are each composed of a halogen-free material.

12. (Currently Amended) A method for producing a synthetic resin card comprising the steps of:

laminating a first outer layer with a first molecular orientation and a second outer layer with a second molecular orientation on front and back surfaces of a substantially planar core ~~layer~~section, respectively, by means of thermal pressing process so that said front and second outer layers are directly adhered to said planar core section, and

forming at least one recording layer on at least one of the first outer layer and the second outer layer,

wherein,

the first and second outer layers are selected so that the difference  $\Delta$  in the angle of orientation between the first and second outer layers is  $20^\circ$  or less so that the synthetic resin card warpage is 1.5 mm or less; and

the first and second outer layers are laminated so that the thicknesses of the first and second outer layers are symmetrical with respect to the core ~~layer~~ section;

~~and a recording layer is formed on at least one of the first outer layer and the second outer layer.~~

13. (New) The method according to claim 12,

wherein,

the first and second outer layers are each biaxially oriented films.

14. (New) The method according to claim 13,

wherein,

the first and second outer layers are comprising of a material selected from the group consisting of polyethylene terephthalate (PET), polyethylene naphthalate (PEN), polypropylene (PP), polyphenylene sulfide (PPS), polystyrene, polyamides, polyvinyl chloride (PVC) and polyvinylidene chloride.

15. (New) The synthetic resin card of claim 1,

wherein,

the core section is made of a material selected from the group consisting of a copolymer of terephthalic acid, cyclohexanedimethanol, and ethylene glycol and a mixture of a polycarbonate resin and a copolymerized polyester resin prepared by replacing 10% to 70% of an ethylene glycol component with cyclohexanedimethanol in polyethylene terephthalate.

16. (New) The method of claim 12,

wherein,

the core section is made of a material selected from the group consisting of a copolymer of terephthalic acid, cyclohexanedimethanol, and ethylene glycol and a mixture of a polycarbonate resin and a copolymerized polyester resin prepared by replacing 10% to 70% of an ethylene glycol component with cyclohexanedimethanol in polyethylene terephthalate.